INFORMATION DISCLOSURE CITATION IN AN APPLICATION				ATTY. DOCKET NO. 49959-118		SERIAL NO. 09/645,690				
			APPLICANT Lizhong Sun, et al.							
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6 · 4	TOT BURNEY, LANG.	U.	S. PATIENT	DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING DATE			
SW	3,889,753	6/17/1975	Richardson							
1	4,090,563	5/23/1978	Lybarger, et al.							
	4,541,945	9/17/1985	Anderson, et al.							
	4,954,142	9/4/1990	Carr, et al.							
	5,084,071	1/28/1992	Nenadic, et	al.						
	5,225,034	7/6/1993	Yu, et al.							
	5,340,370	8/23/1994	Cadien, et al.							
	5,478,436	12/26/1995	Winebarger, et al.							
	5,527,423	6/18/1996	Neville, et al.							
	5,645,682	7/8/1997	Skrovan			<u> </u>				
	5,662,769	9/2/1997	Schonauer,	et al.						
	5,509,970	4/23/1996	Shiramizu							
	5,876,508	3/2/1999	Wu, et al.							
V	5,879,226	3/9/1999	Robinson							
10	Section Sections	FORI	CIGN PATI	ENT DOCUMEN	TS .		Translation			
EXAMINER'S INITIALS	PATENT NO.	DATE	C	OUNTRY	CLASS	SUBCLASS	Yes No			
5	0 401 147	12/5/1990	EPO							
L	39 39 661	6/13/1991	DE							
	0 496 605	7/29/1992	EPO							
	2 722 511	1/19/1996	FR							
V	0 860 860	8/26/1998	EPO							
				r, Title, Date, Per			<u> </u>			
GN)	Hymes, et al., "The Challenges of the Copper CMP Clean", Semiconductor International, pp. 117-122 (1998).									
	Pak, "Impact of EDTA on Junction and Photolith Qualities", Extended Abstracts, October 1980, yol. 80, no. 2, pp 1241-1243.									
EXAMINE	DATE CONSIDERED									
Ser	Ir Illin	<u></u>		8/18/02	8/10/02					

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INFO	ORMATION		ATTY. DOCKET NO.		SERIAL NO.							
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			APPLICANT Lizhong Sun, et al.									
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EXAMINER'S	<u> </u>			1000 CAUTA DI CATO	T T	T S	FIL	ING DATE				
INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS						
aw	5,981,454	11/9/1999	Small				<u></u>					
	6,033,993	3/7/2000	Love, Jr. et a	l.		<u> </u>						
	5,830,280	11/3/1998	Sato, et al.			ļ						
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INITIALS	PATENT NO.	DATE	cc	DUNTRY	CLASS	SUBCLASS	Yes	No				
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Sw	· ·	Kern, "Radiochemical Study of Semiconductor Surface Contamination", RCA Review, June 1970, vol. 31, pp 207-264.										
	Kaufman, F.B., et al., "Chemical-Mechanical Polishing for Fabricating Patterned W Metal											
V	Features as Chip Interconnects", J. Electrochem. Society, pp 3460-3465 (1991).											
Qu	Brusic, V., et al., "Copper Corrosion with and without Inhibitors", J. Electrochem. Soc., V 138, No. 8, August 1991.											
	oruary 19-20	, 1998	CMP-MIC									
	Conference.		· · · · · · · · · · · · · · · · · · ·				$\overline{}$					
EXAMINER DATE CONSIDERED												
	CA : 1 1111_	_	I	2/16/02								

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.